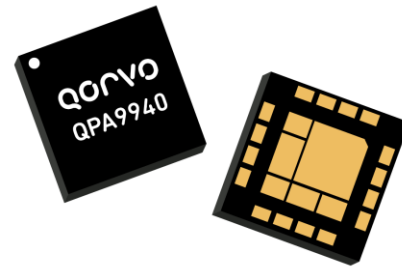


Product Overview

The QPA9940 is a high-efficiency, linearizable power amplifier targeting Band 40 small-cell wireless infrastructure systems. Using InGaP/GaAs HBT technology, the product delivers high efficiency of 31% at +28dBm average output power while providing excellent DPD linearized ACPR of -50 dBc for signal bandwidths of up to 100MHz.

The QPA9940 is housed in a 5x5mm SMT package. It is pin-to-pin compatible to QPA9901, QPA9903 and QPA9908 (high-efficiency small cell PA).

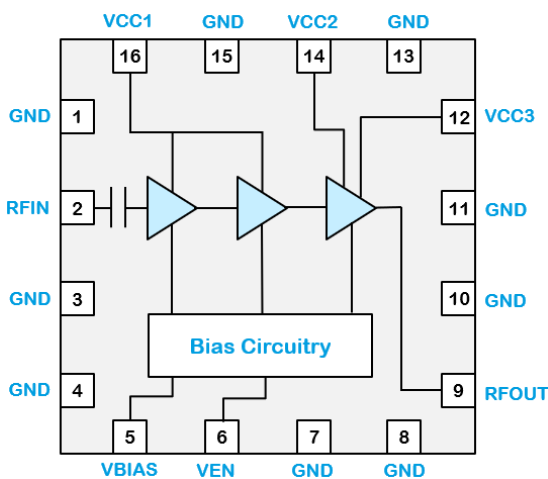


16 Pad 5 x 5 mm Package

Key Features

- 2300 – 2400 MHz
- 34.5 dB Gain
- Over 36 dBm P3dB
- 31% PAE at +28 dBm power output
- -50 dBc ACPR DPD Linearized at +28 dBm Power Output with 5-carrier signal
- 1.8V Logic Compatible PA ON/OFF Control
- On Chip ESD Protection
- 5 x 5 mm Package

Functional Block Diagram



Top View

Applications

- 4G/5G Small-cell BTS
- 5G M-MIMO
- Repeaters / DAS
- Mobile Infrastructure
- General Purpose Wireless

Ordering Information

| Part No. | Description |
|---------------|---------------------|
| QPA9940TR13 | 2500pcs on 13" reel |
| QPA9940EVB-01 | 2300-2400 MHz EVB |

Absolute Maximum Ratings

| Parameter | Rating |
|--|----------------|
| Storage Temperature | -55 to +125 °C |
| RF Input Power, Pulsed CW, 50 Ω ⁽¹⁾ | +10 dBm |
| Device Voltage (V _{CC}) | +5.5 V |

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability.

1. 2300-2400 MHz, Pulsed CW, 10% duty cycle, 100us period

Recommended Operating Conditions

| Parameter | Min | Typ | Max | Units |
|--|-------|-----|-------|-------|
| Device Voltage (V _{CC}) | +4.75 | +5 | +5.25 | V |
| T _{CASE} | -40 | | +105 | °C |
| T _j for >10 ⁶ hours MTTF | | | +175 | °C |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications

| Parameter | Conditions ⁽¹⁾ | Min | Typ | Max | Units |
|---------------------------------------|--|------|------|-----------------|-------|
| Operational Frequency Range | | 2300 | | 2400 | MHz |
| Test Frequency | | | 2350 | | MHz |
| Gain ⁽²⁾ | At +28dBm P _{out} and room temperature | 32 | 34.5 | | dB |
| Input Return Loss | | | -17 | | dB |
| Output Return Loss | | | -15 | | dB |
| Output P _{3dB} | 10 μs pulse width, 10% duty cycle | 35.1 | +36 | | dBm |
| Power Added Efficiency ⁽²⁾ | P _{out} = +28 dBm | 28.1 | 31 | | % |
| ACPR (Uncorrected) ⁽²⁾ | P _{out} = +28 dBm | | -31 | -28.4 | dBc |
| ACPR (Uncorrected) ⁽³⁾ | P _{out} = +28 dBm | | -29 | | dBc |
| ACPR (Corrected) ⁽³⁾ | P _{out} = +28 dBm | | -50 | | dBc |
| Quiescent Current, I _{CC} | Pins 12, 14 and 16 | | 100 | | mA |
| Total Operating Current | Pin 5, 12, 14 and 16, P _{out} = +28 dBm | | 406 | | mA |
| Thermal Resistance, θ _{JC} | Junction to case | | 23.3 | | °C/W |
| V _{EN} High | | 1.17 | 1.8 | V _{CC} | V |
| V _{EN} Low | | 0 | 0 | 0.63 | V |
| 2nd Harmonic | P _{out} = +28 dBm | | -40 | | dBc |
| 3rd Harmonic | P _{out} = +28 dBm | | -54 | | dBc |
| Turn-on time | Measured from 50% PA enable voltage level to 90% of RF amplitude | | 0.5 | | us |

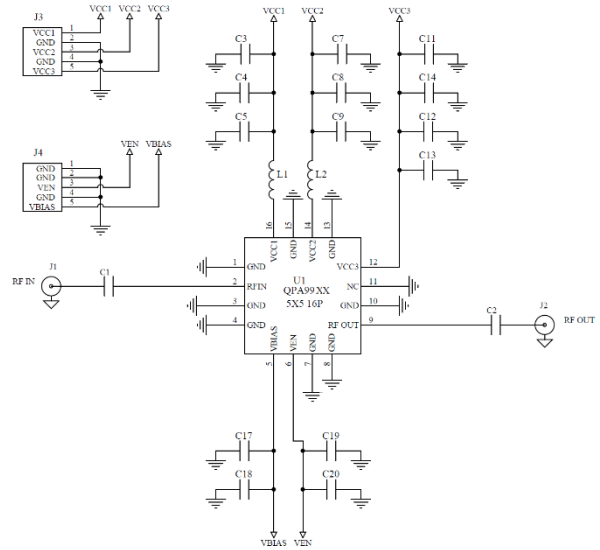
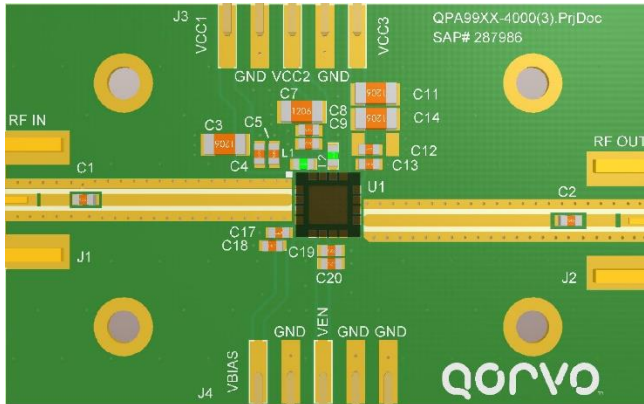
Notes:

1. Test conditions unless otherwise noted: All V_{CC} & V_{BIAS} = +5.0 V, V_{EN} = +1.8 V, Temp = +25 °C, 50 Ω system.
2. LTE, 20 MHz E-UTRA Test Mode 1.1 or 3.1, PAR = 8.5 dB at 0.01% probability.
3. LTE, 20 MHz x 5 E-UTRA Test Mode 1.1 or 3.1, PAR = 8.5 dB at 0.01% probability.

Power Amplifier Enable Logic Table

| Parameter | High | Low |
|-----------------|--------------------|---------------------|
| V _{EN} | Power Amplifier ON | Power Amplifier OFF |

QPA9940 EVB Layout and Schematic



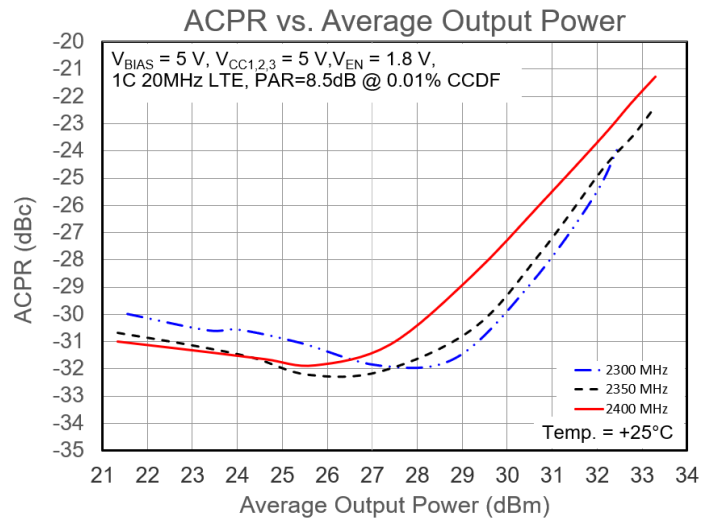
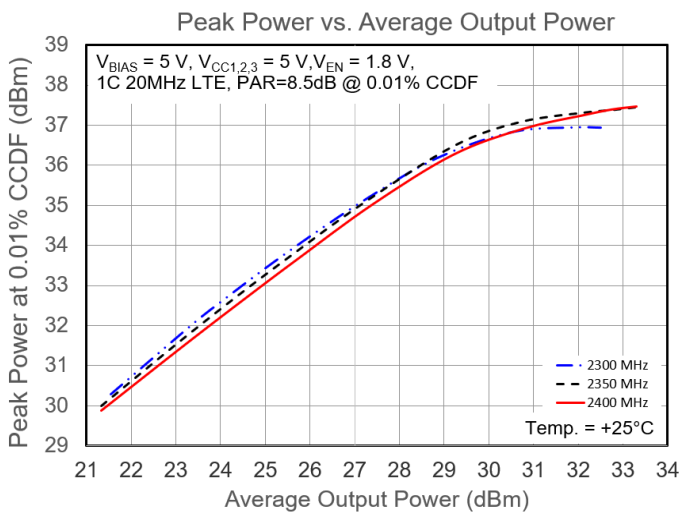
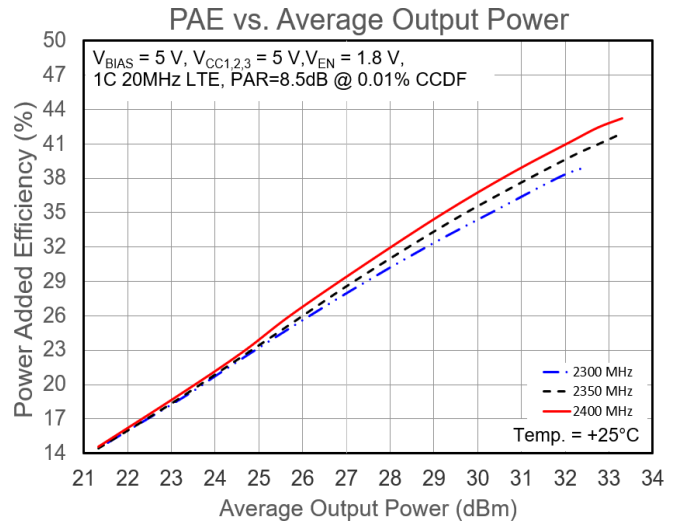
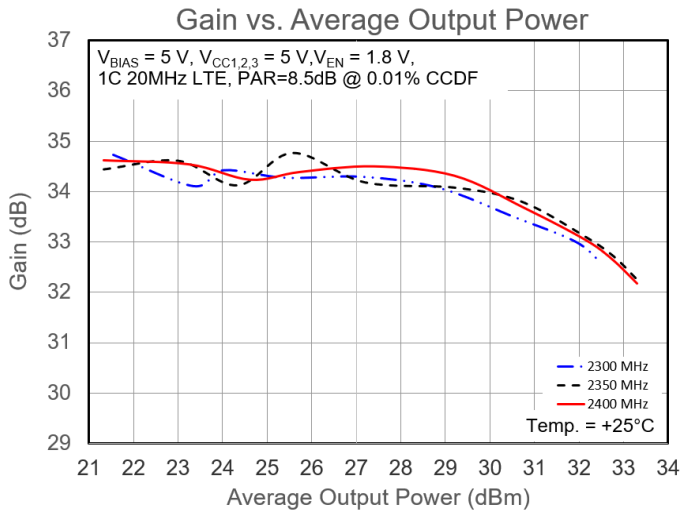
Notes:

1. See Evaluation Board PCB Information for material and stack up.

Bill of Materials – QPA9940EVB-01

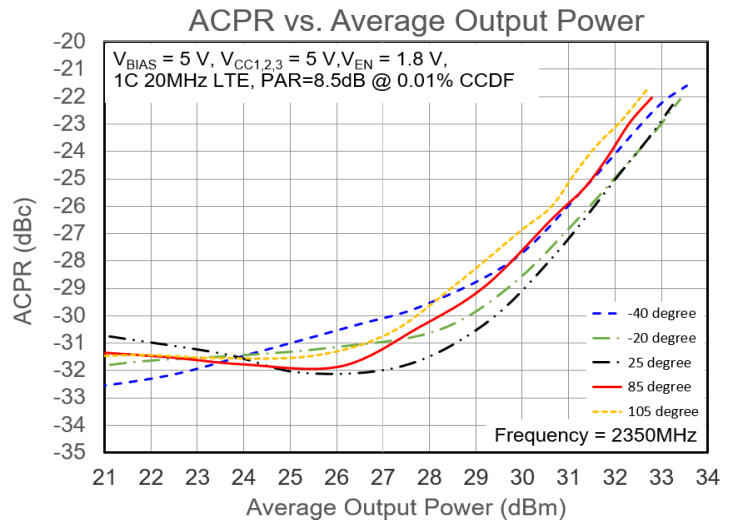
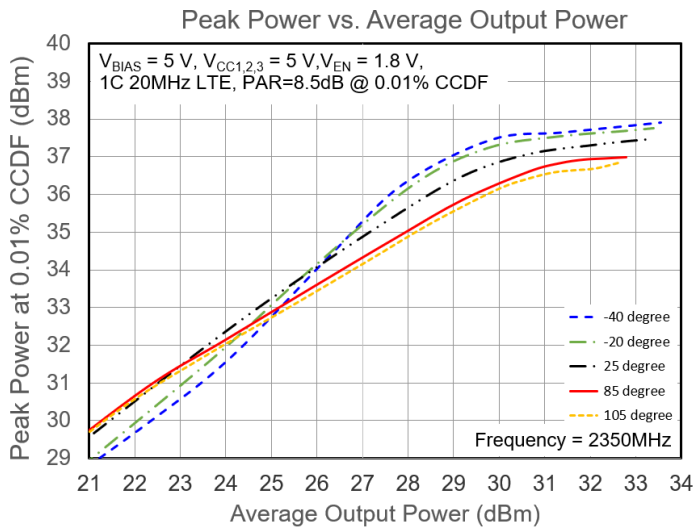
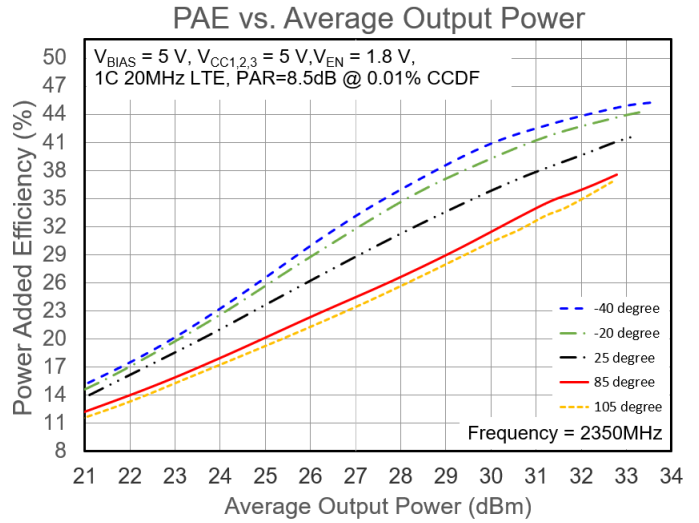
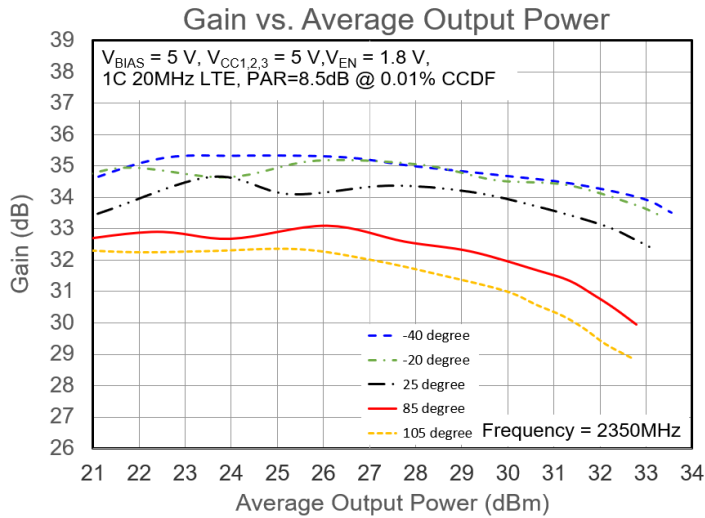
| Reference Des. | Value | Description | Manuf. | Part Number |
|-----------------------|---------|--|---------|-------------|
| U1 | - | Amplifier, QPA9940 2300-2400MHz, High-Efficiency | Qorvo | QPA9940 |
| C1, C2 | 100 pF | CAP,100 pF, 0603, 5%, 50V, C0G | various | |
| C5, C9, C13, C17, C19 | 1000 pF | CAP,1000 pF, 0603, 5%, 50V, C0G | various | |
| C4, C8, C12, C18, C20 | 0.1 μF | CAP,0.1 μF, 0603, 10%, 50V, X7R | various | |
| C3, C7, C14 | 10 μF | CAP, 10 μF, 1206, 25V | various | |
| L1, L2 | 0 Ω | RES 0 Ω, 0603, 1/16W, Chip | various | |
| J1, J2 | - | CONN. RF. SMA. F. STRT. Edge Mount | various | |
| J3, J4 | - | Connector, 5 Pin | various | |

Performance Plots - LTE



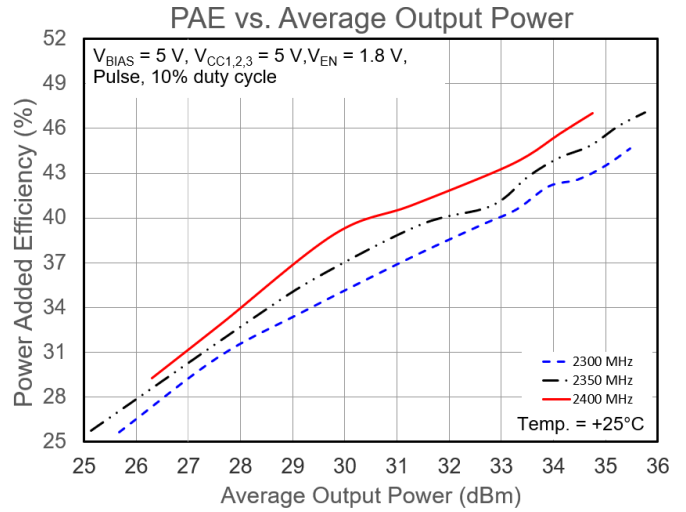
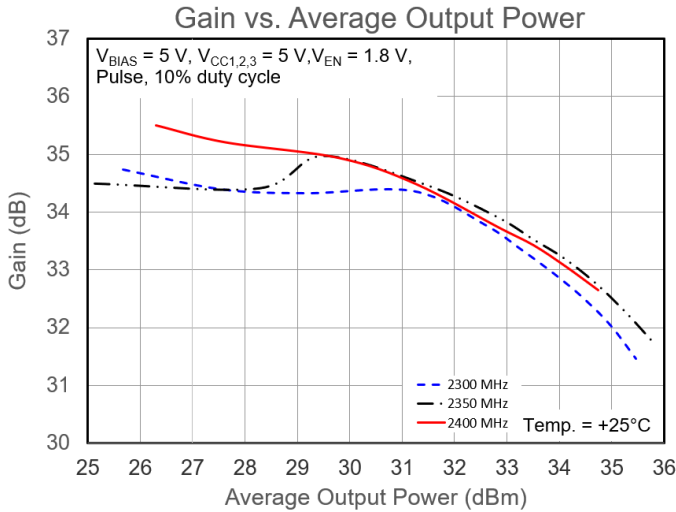
Test conditions unless otherwise noted: $V_{BIAS} = 5\text{ V}, V_{CC1,2,3} = 5\text{ V}, V_{EN} = 1.8\text{ V}, T = +25^\circ\text{C}$, tested using a single-carrier, 20 MHz LTE signal with 8.5 dB PAR at 0.01% CCDF on a reference design fixture.

Performance Plots - LTE

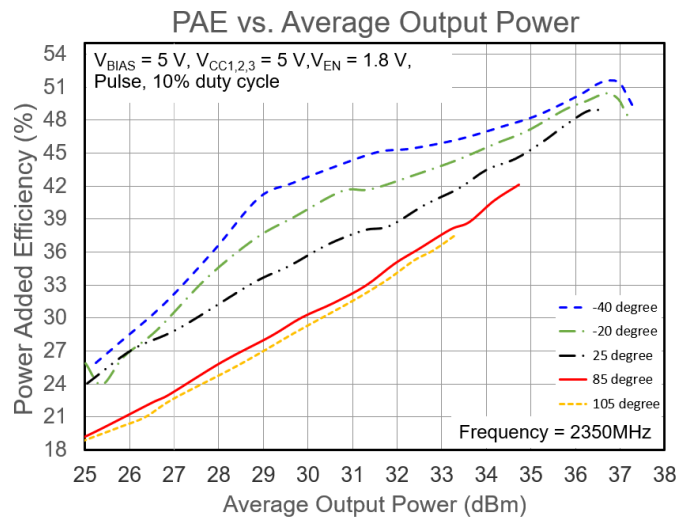
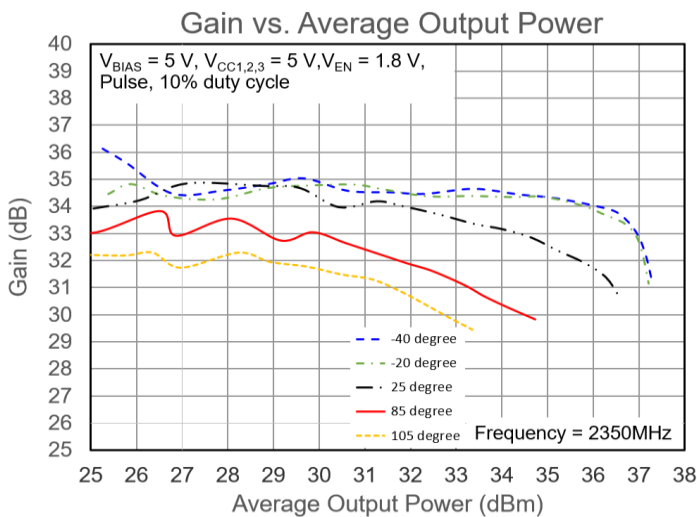


Test conditions unless otherwise noted: $V_{BIAS} = 5\text{ V}, V_{CC1,2,3} = 5\text{ V}, V_{EN} = 1.8\text{ V}$, tested at 2350 MHz using a single-carrier, 20 MHz LTE signal with 8.5 dB PAR at 0.01% CCDF on a reference design fixture.

Performance Plots - Pulse

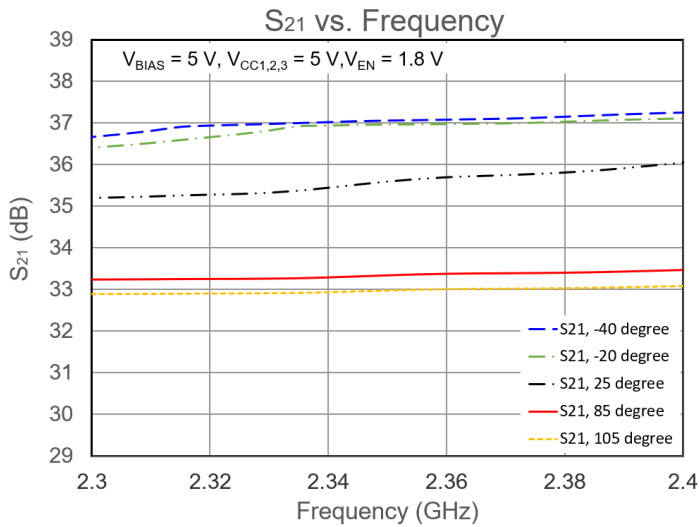
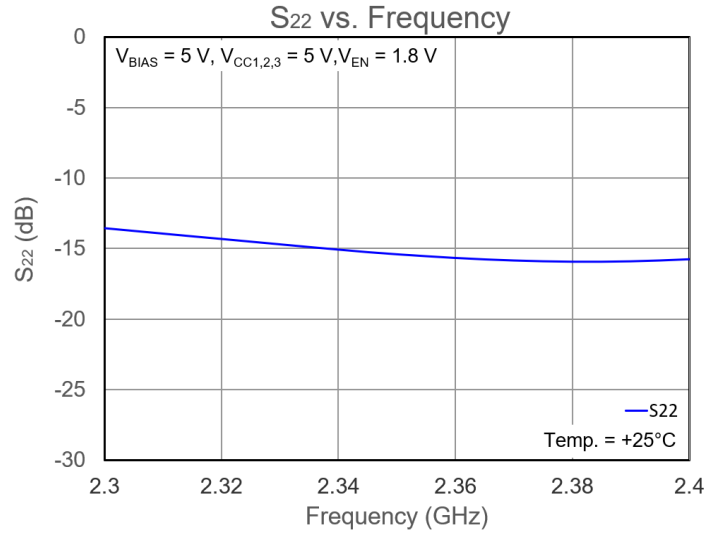
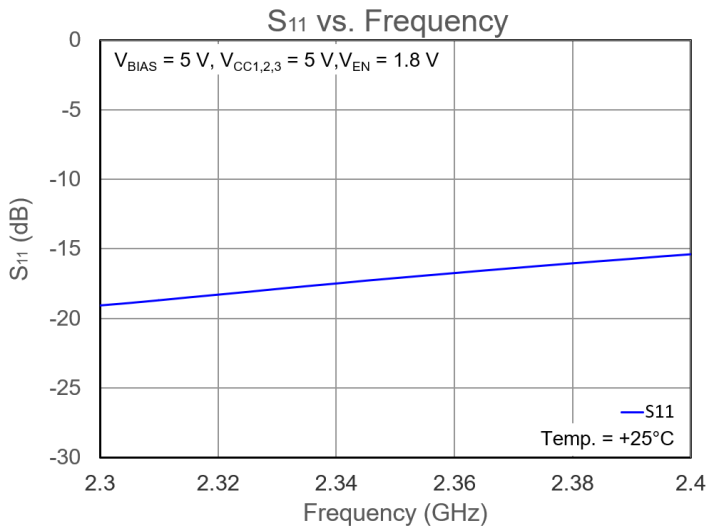


Test conditions unless otherwise noted: $V_{BIAS} = 5\text{ V}, V_{CC1,2,3} = 5\text{ V}, V_{EN} = 1.8\text{ V}, T = +25^\circ\text{C}$, tested using a pulse signal, 10% duty cycle.



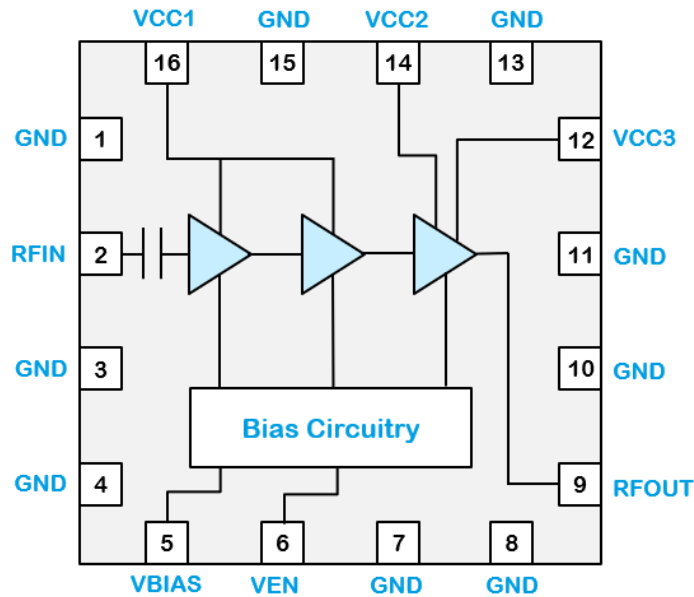
Test conditions unless otherwise noted: $V_{BIAS} = 5\text{ V}, V_{CC1,2,3} = 5\text{ V}, V_{EN} = 1.8\text{ V}$, tested at 2350 MHz using a pulse signal, 10% duty cycle.

Performance Plots – S-parameters



Test conditions unless otherwise noted: $V_{BIAS} = 5\text{ V}, V_{CC1,2,3} = 5\text{ V}, V_{EN} = 1.8\text{ V}$.

Pad Configuration and Description

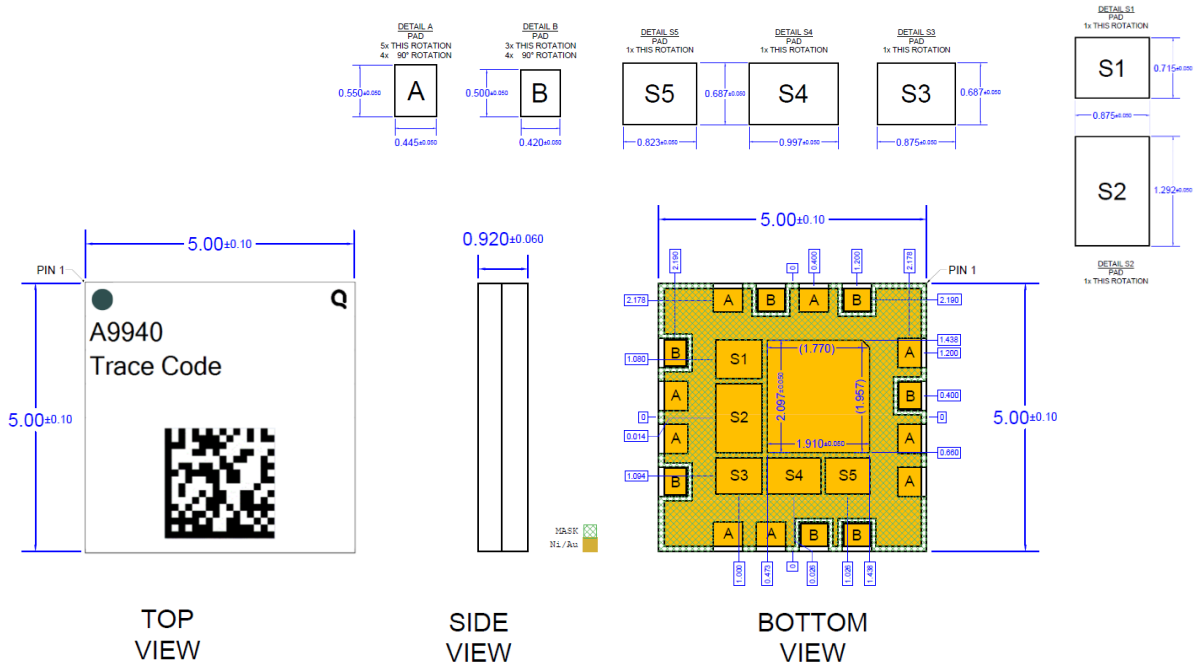


Top View

| Pad No. | Label | Description |
|------------------------------|-------------------|---|
| 1, 3, 4, 7, 8,10, 11, 13, 15 | GND | Ground connection. |
| 2 | RF _{IN} | RF input, internally matched to 50Ω and DC blocked. |
| 5 | V _{BIAS} | Bias circuit supply voltage |
| 6 | V _{EN} | Amplifier enable voltage (regulated internally) |
| 9 | RF _{OUT} | RF output, internally matched to 50Ω and DC shorted. External DC blocking capacitor required |
| 12 | V _{CC3} | Supply voltage for the various amplifier stages |
| 14 | V _{CC2} | Supply voltage for the various amplifier stages |
| 16 | V _{CC1} | Driver stage supply voltage |
| Backside Paddle | GND | Ground connection. The back side of the package should be connected to the ground plane through as short of a connection as possible. PCB via holes under the device are recommended. |

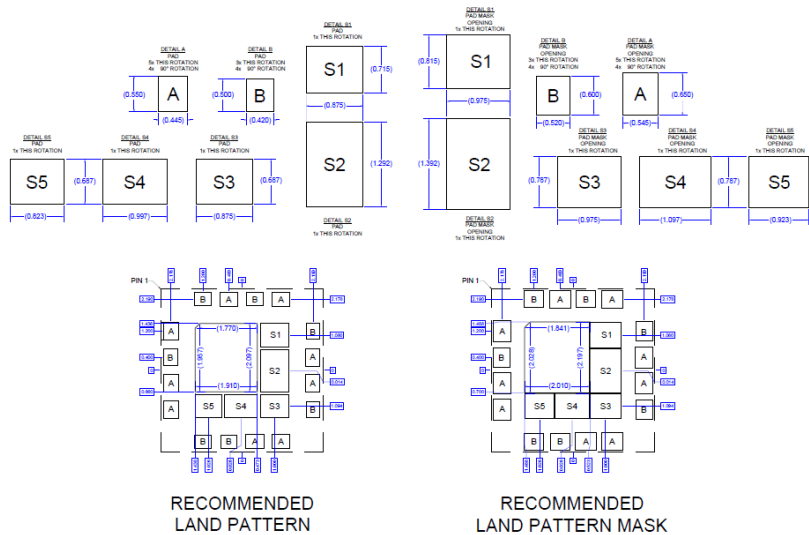
Package Marking and Dimensions

Marking: Pin 1 Indicator and Qorvo Logo
 Part Number – QPA9940
 Trace Code – XXXXXX Up to 8 Characters to be Assigned by sub-Contractor



- Notes:
1. All dimensions are in millimeters. Angles are in degrees.
 2. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.
 3. Contact plating: ENEPIG

PCB Mounting Pattern

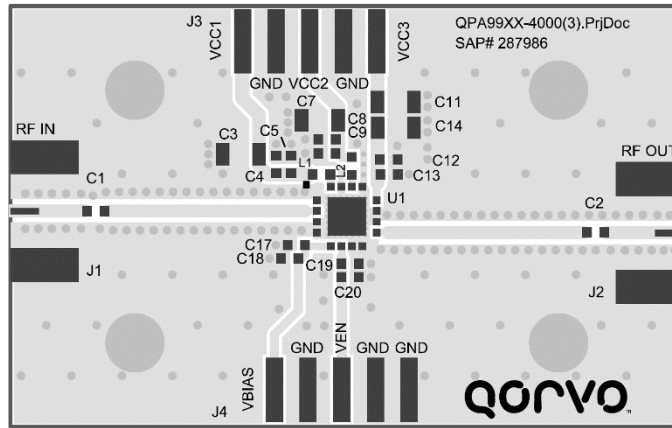


Evaluation Board PCB Information

PC Board Layout

| Layer | Name | Material | Thickness | Constant |
|-------|--------------|---------------|-----------|----------|
| 1 | Top Overlay | | | |
| 2 | Top Solder | Solder Resist | 0.40 mil | 3.5 |
| 3 | Top Layer | Copper | 1.40 mil | |
| 4 | Dielectric1 | RO4350 | 20.00 mil | 3.48 |
| 5 | Bottom Layer | Copper | 1.40 mil | |

Total thickness: 23.2mill

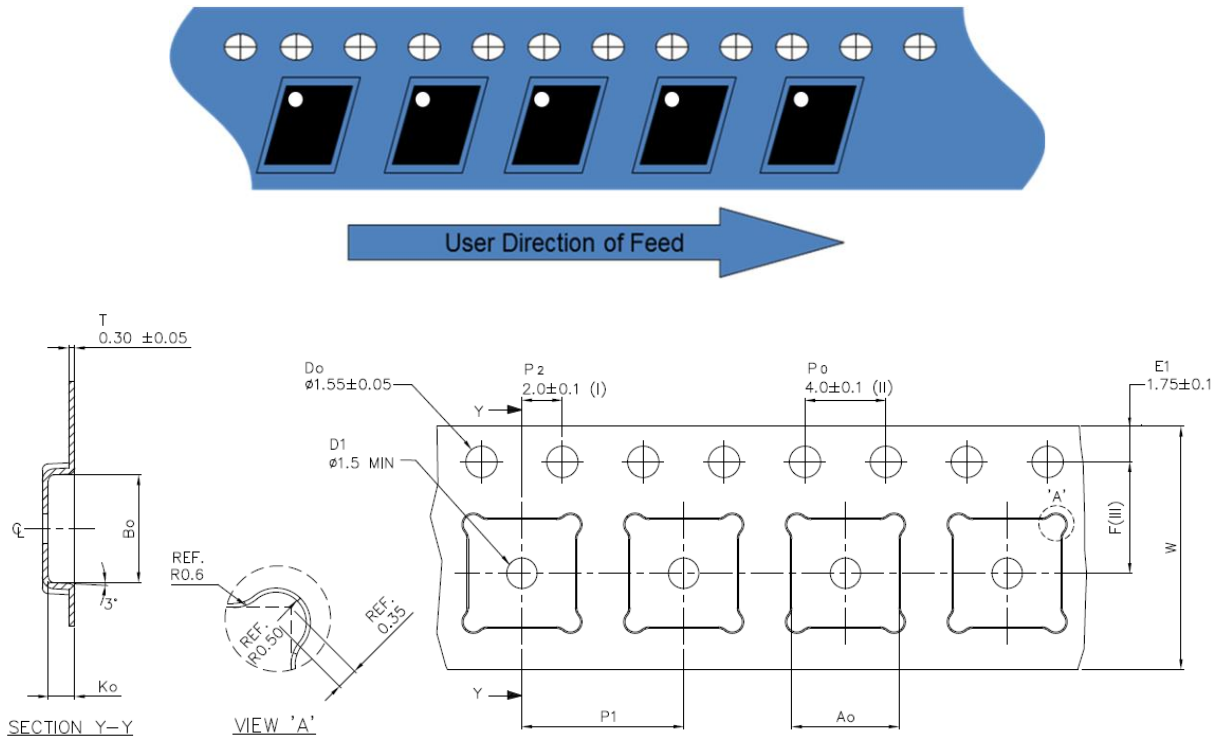


Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Via holes are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.10").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.

Tape and Reel Information – Carrier and Cover Tape Dimensions

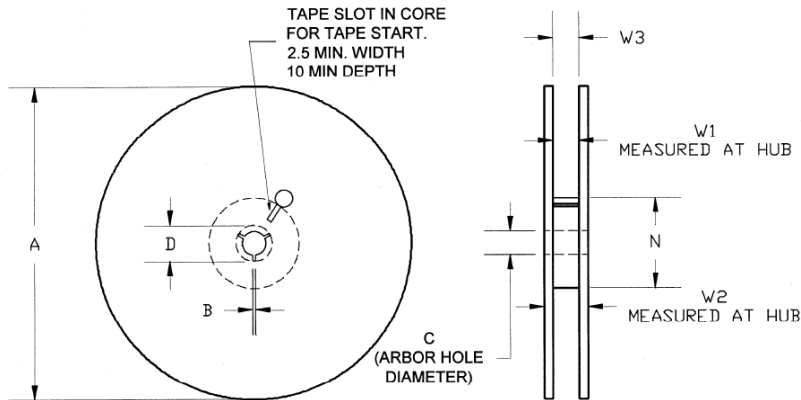
Tape and reel specifications for this part are also available on the Qorvo website.
Standard T/R size = 2500 pieces on a 13" reel.



| Feature | Measure | Symbol | Size (in) | Size (mm) |
|---------------------|--|--------|-----------|-----------|
| Cavity | Length | A0 | 0.209 | 5.3 |
| | Width | B0 | 0.209 | 5.3 |
| | Depth | K0 | 0.051 | 1.3 |
| | Pitch | P1 | 0.315 | 8.0 |
| Centerline Distance | Cavity to Perforation - Length Direction | P2 | 0.079 | 2.0 |
| | Cavity to Perforation - Width Direction | F | 0.217 | 5.5 |
| Cover Tape | Width | C | 0.362 | 9.2 |
| Carrier Tape | Width | W | 0.472 | 12 |

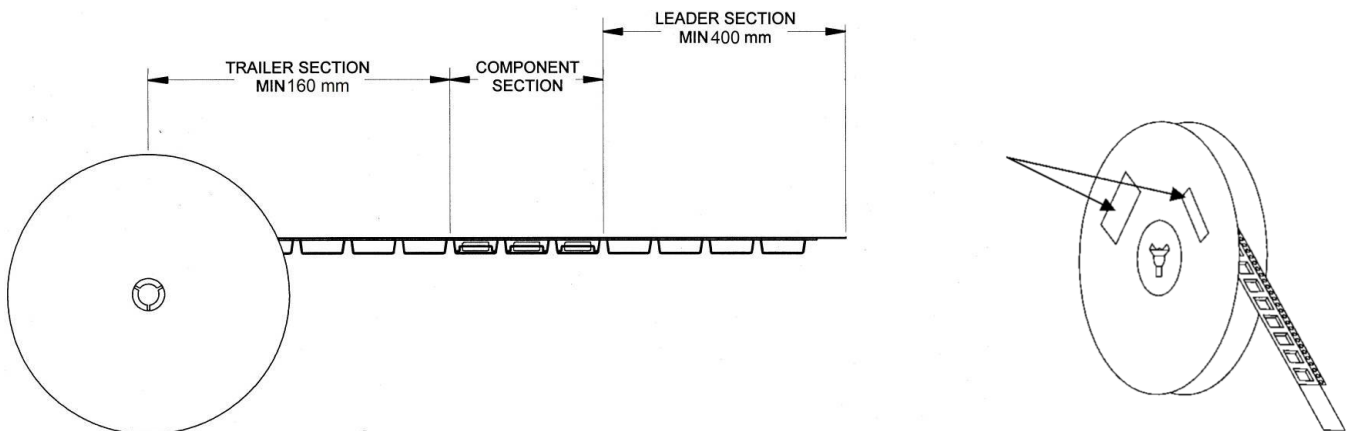
Tape and Reel Information – Reel Dimensions

Packaging reels are used to prevent damage to devices during shipping and storage, loaded carrier tape is typically wound onto a plastic take-up reel. The reel size is 13" diameter. The reels are made from high-impact injection-molded polystyrene (HIPS), which offers mechanical and ESD protection to packaged devices.



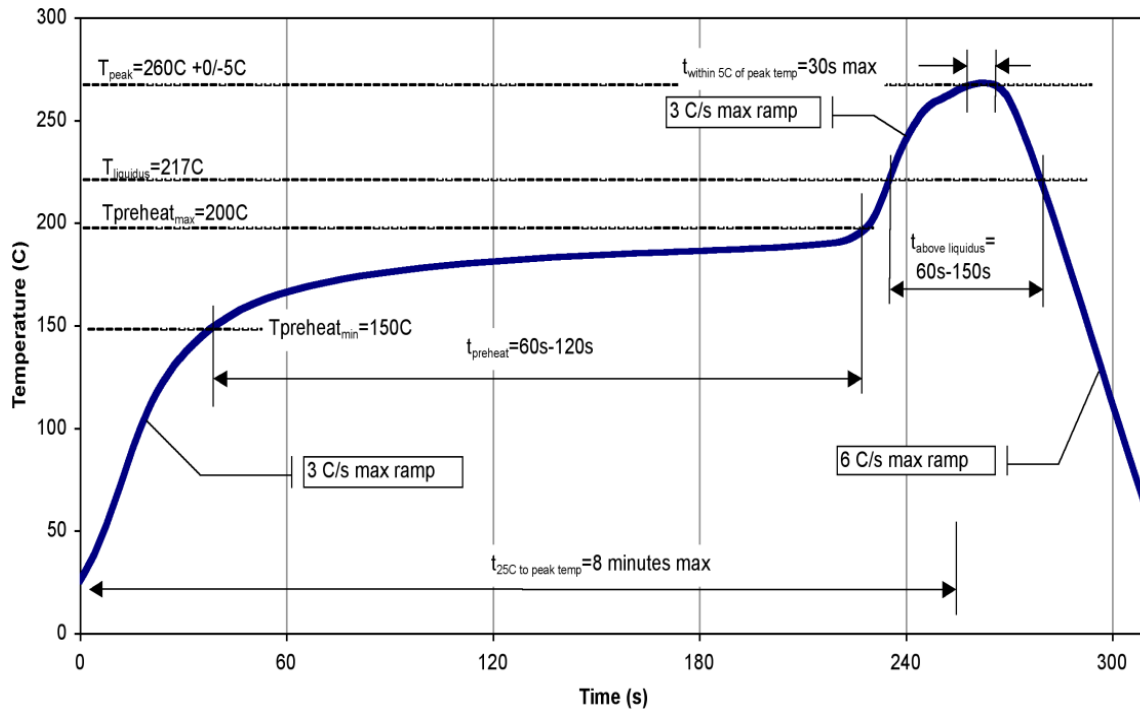
| Feature | Measure | Symbol | Size (in) | Size (mm) |
|---------|----------------------|--------|-----------|-----------|
| Flange | Diameter | A | 12.992 | 330.00 |
| | Thickness | W2 | 0.717 | 18.20 |
| | Space Between Flange | W1 | 0.504 | 12.80 |
| Hub | Outer Diameter | N | 4.016 | 102.00 |
| | Arbor Hole Diameter | C | 0.512 | 13.00 |
| | Key Slit Width | B | 0.079 | 2.00 |
| | Key Slit Diameter | D | 0.795 | 20.2 |

Tape and Reel Information – Tape Length and Label Placement



- Notes:
1. Empty part cavities at the trailing and leading ends are sealed with cover tape. See EIA 481-1-A.
 2. Labels are placed on the flange opposite the sprockets in the carrier tape.

Recommended Solder Temperature Profile



Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|----------|--------------------------|
| ESD – Human Body Model (HBM) | Class 1C | ESDA / JEDEC JS-001-2012 |
| ESD – Charged Device Model (CDM) | Class C3 | JEDEC JESD22-C101F |
| MSL – Moisture Sensitivity Level | Level 3 | IPC/JEDEC J-STD-020 |



Caution!
ESD-Sensitive Device

Solderability

Compatible with both lead-free (260°C max. reflow temp.) and tin/lead (245°C max. reflow temp.) soldering processes. Solder profiles available upon request.

Contact plating: ENEPIG

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Product uses RoHS Exemption 7c-I to meet RoHS Compliance requirements.
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: www.qorvo.com

Tel: 1-844-890-8163

Email: customer.support@qorvo.com

For technical questions and application information:

Email: appsupport@qorvo.com

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